

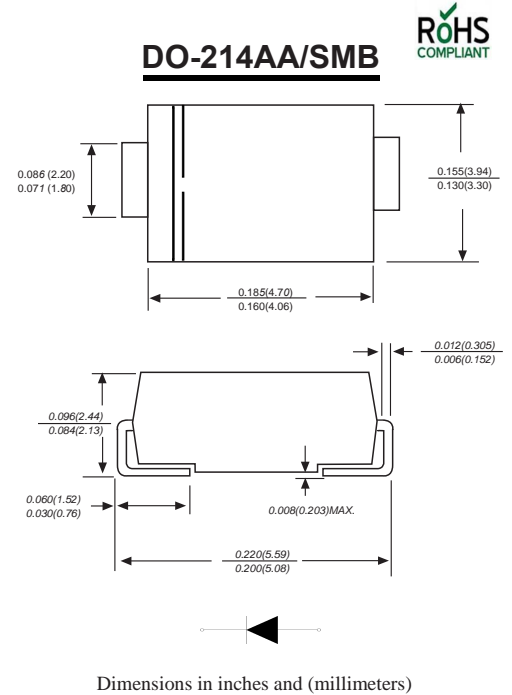
## SURFACE MOUNT SUPER FAST RECOVERY RECTIFIER

### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
- ◆ 250°C/10 seconds at terminals  
Glass passivated chip junction

### Mechanical Data

- Case :** JEDEC DO-214AA/SMB Molded plastic body  
**Terminals :** Solder plated, solderable per MIL-STD-750, Method 2026  
**Polarity :** Polarity symbol marking on body  
**Mounting Position :** Any  
**Weight :** 0.003 ounce, 0.095 grams



### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

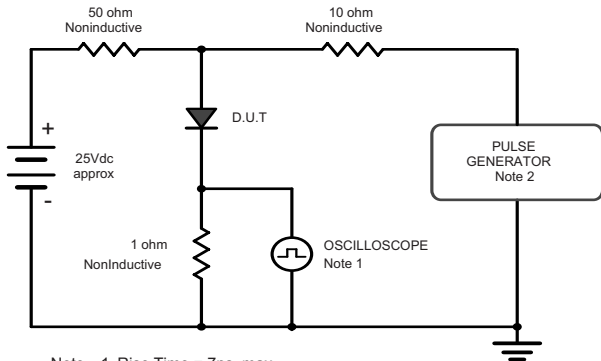
Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	MDD ES2AB	MDD ES2BB	MDD ES2CB	MDD ES2DB	MDD ES2EB	MDD ES2GB	MDD ES2JB	UNITS
Marking Code									
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	150	200	300	400	600	V
Maximum RMS voltage	$V_{RMS}$	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	$V_{DC}$	50	100	150	200	300	400	600	V
Maximum average forward rectified current at $T_L=125^\circ\text{C}$	$I_{(AV)}$	2.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	60							A
Maximum instantaneous forward voltage at 2.0A	$V_F$	1			1.25		1.68		V
Maximum DC reverse current at rated DC blocking voltage	$I_R$	5 100							uA
Maximum reverse recovery time (NOTE 1)	$t_{rr}$	35							ns
Typical junction capacitance (NOTE 2)	$C_J$	40							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$ $R_{\theta JC}$	60 20							$^\circ\text{C}/\text{W}$
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150							$^\circ\text{C}$

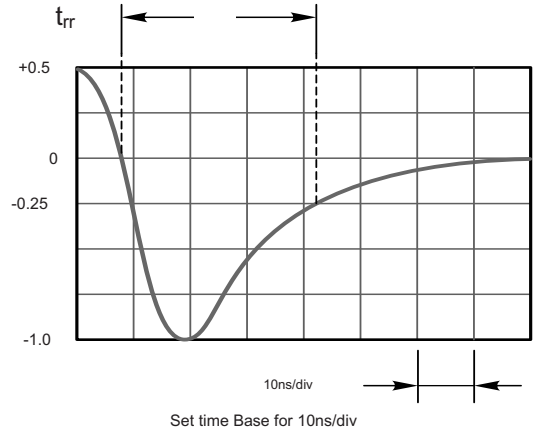
- Note:** 1. Reverse recovery condition  $I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$   
 2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
 3. P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas

## Ratings And Characteristic Curves

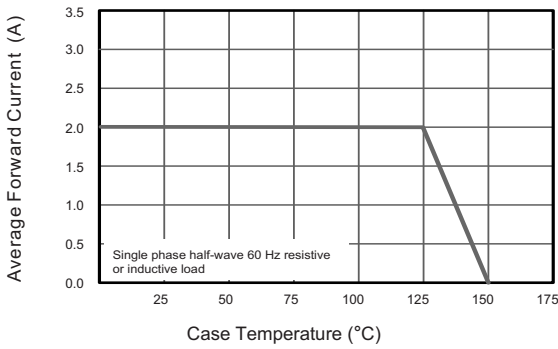
**Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram**



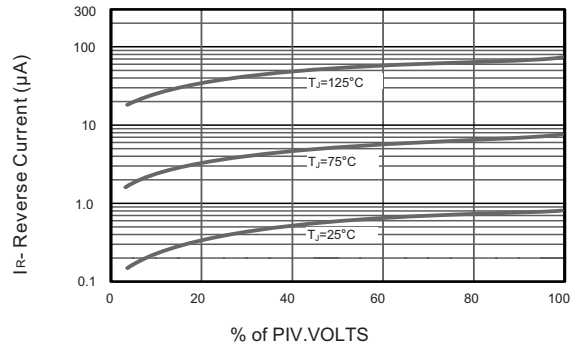
Note: 1. Rise Time = 7ns, max.  
Input Impedance = 1megohm, 22pF.  
2. Rise Time = 10ns, max.  
Source Impedance = 50 ohms.



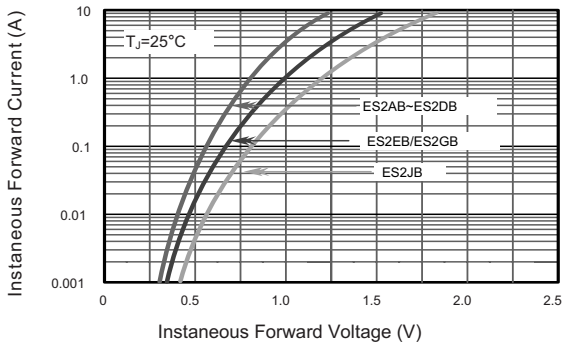
**Fig.2 Maximum Average Forward Current Rating**



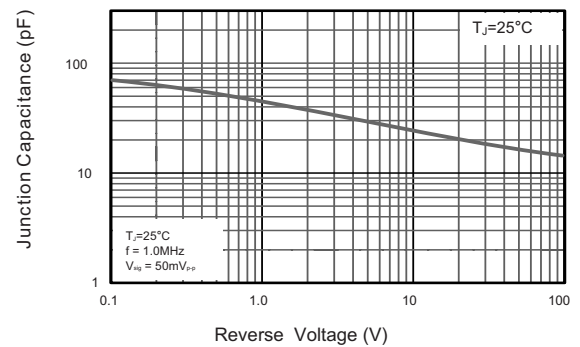
**Fig.3 Typical Reverse Characteristics**



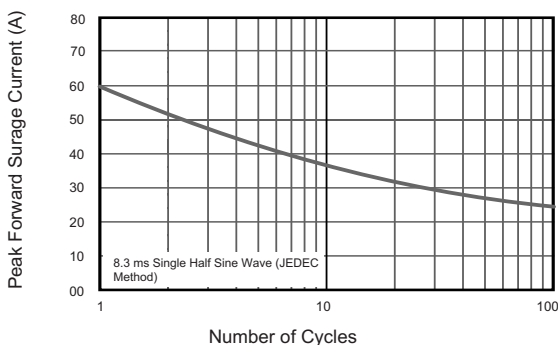
**Fig.4 Typical Forward Characteristics**



**Fig.5 Typical Junction Capacitance**

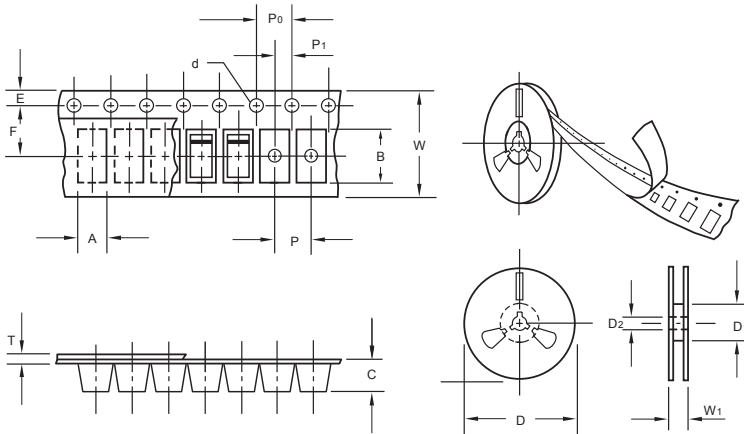


**Fig.6 Maximum Non-Repetitive Peak Forward Surge Current**



The curve above is for reference only.

## Packing information



unit:mm

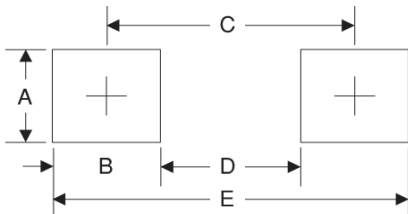
Item	Symbol	Tolerance	SMB
Carrier width	A	0.1	3.81
Carrier length	B	0.1	5.41
Carrier depth	C	0.1	2.42
Sprocket hole	d	0.05	1 5.0
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D <sub>1</sub>	min	50.00
Feed hole diameter	D <sub>2</sub>	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.55
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P <sub>0</sub>	0.1	4.00
Embossment center	P <sub>1</sub>	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	12.00
Reel width	W <sub>1</sub>	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA, (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMB	13"	3,000	4.0	6,000	190*190*41	330	365*365*360	48,000	14.0

## Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	2.8	0.110
B	2.4	0.094
C	4.6	0.181
D	2.2	0.086
E	7.0	0.276